



Thin Film Microcircuits - Design Guidelines

SUBSTRATES	Standard materials	Alumina 96%, 99.5%, 99.6% Aluminium nitride (AlN) Fused quartz
	Other materials	Ferrite Glass Sapphire Silicon Silicon carbide
	Standard thicknesses	0.127, 0.254, 0.381, 0.508, 0.635, 0.762, 1.016 mm
	Thickness tolerances	As fired $\pm 10\%$ Polished $\pm 13 \mu\text{m}$
	Standard sizes	50.8 x 50.8, 57.15 x 57.15, 76.2 x 76.2, 101.6 x 101.6, 114.3 x 114.3 mm
	Surface finish - Alumina	As fired $< 0.125 \mu\text{m Ra}$ Polished $< 0.025 \mu\text{m Ra}$
	Surface finish - AlN	As fired $1.6 \mu\text{m Ra}$ Polished $< 0.05 \mu\text{m Ra}$
	Camber	As fired $0.05 \text{ mm} / 25 \text{ mm}$ Polished $0.025 \text{ mm} / 25 \text{ mm}$
IMAGING	Maximum circuit size	127 x 100 mm
	Minimum pattern to substrate edge	20 μm
	Typical pattern tolerance	$\pm 20 \mu\text{m}$
	Typical layer alignment tolerance	$\pm 20 \mu\text{m}$
CONDUCTORS	Minimum line width/space	10 μm
	Typical line width/space	25 μm
	Minimum line width tolerance	$\pm 3 \mu\text{m}$
	Typical line width tolerance	$\pm 10 \mu\text{m}$
	Minimum space tolerance	$\pm 3 \mu\text{m}$
	Typical space tolerance	$\pm 10 \mu\text{m}$
	Minimum metallisation around vias	100 μm
METALLISED THRU HOLES / FILLED VIAS	Minimum aspect ratio (Hole diameter : substrate thickness)	0.67:1
	Typical hole diameter	Substrate thickness
	Minimum hole diameter	67% of substrate thickness
	Minimum hole to hole web thickness or hole to edge web distance	Substrate thickness
RESISTORS	Nominal sheet resistance	10 - 200 ohms/sq
	Preferred sheet resistance	50 or 100 ohms/sq
	Non-trimmed tolerance	$\pm 20\%$
	Trimmed tolerance	$\pm 0.2\%$
	Pre-trimmed design value	-20%
	Minimum length/width	0.1 mm
	Minimum termination pad size	0.1 mm x 0.1 mm
	Minimum distance between resistors	0.05 mm

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LASER PROFILING	Maximum substrate thickness for profiling	1.0 mm	
	Lasered feature tolerance	± 30 µm	
	Lasered feature position tolerance	± 30 µm	
	Minimum lasered feature to pattern gap	30 µm	
	Lasered feature to pattern tolerance	± 30 µm	
	Typical laser taper	± 50 µm / mm	
	Minimum distance hole to hole/hole to edge	= Substrate thickness	
	Maximum substrate size	150 x 150 mm	
DIAMOND SAWING	Maximum substrate thickness for dicing	2.0 mm	
	Maximum tile size	Rectangular:	127 x 127 mm
		Circular:	150 mm dia.
	Minimum distance pattern to edge	0.030 mm	
	Typical distance pattern to edge	0.050 mm	
	Minimum dicing tolerance	±0.025 mm	
	Typical dicing tolerance	±0.050 mm	
	Typical blade width	Substrate Thickness	Blade Width
		<0.5 mm	0.2 mm
		0.5-1.0 mm	0.3 mm
		>1.0 mm	0.4 mm
METALLISATIONS	Adhesion layers	Ti, TiW, NiCr, Cr	
	Barrier layers	TiW, Pt, Pd, Ni	
	Conductor layers	Cu, Au	
	Resistive layers	NiCr, TaN	
	Dielectrics/Passivations	Polyimide	
	Pre-deposited solder	AuSn. Typically 3 - 5 µm thick	
PLATINGS	Electrolytic	Cu, Ni, Au. Typically 1 - 6 µm thick	
	Typical plating thickness tolerance	± 25%	
DATA FORMAT	DWG, DXF, Gerber, GDSII	AutoCAD preferred	
	Lines	Closed polylines	
OTHER	Air bridges, multi-layers, double sided circuits, edge wrapovers, solid vias, fully sputtered or plated-up conductors, RIE or wet etched patterns, shadow masking, sputter up or down, evaporation, laser profiling/scribing/serial numbering, sub-assembly.		
GENERAL	Actual capabilities are application specific and will depend on the interactions between the substrate material, metallisation scheme, vias, apertures, line widths, line spacing, conductor thickness, resistor geometry, etc. Generally the more complicated the circuit and the tighter the tolerances the lower the yield and thus the higher the cost. Selection of metallisation schemes is dependant on requirements for solderability, wire bondability and temperature resistance as well as electrical and dimensional performance.		
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To discuss your application in detail please contact our Technical Sales Department who will be pleased to assist you.			

LEW Techniques Ltd

www.lewtec.co.uk +44 (0)1823 286 698 info@lewtec.co.uk

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